

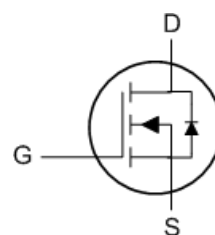
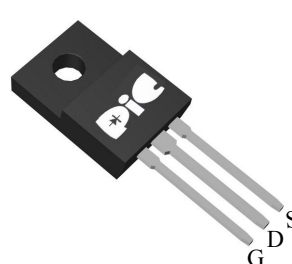
### ➤ General Description

This PAN60TF06GF N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent  $R_{ds(On)}$  performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

### ➤ Feature

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent  $C_{dv}/dt$  effect decline
- Advanced high cell density Trenchtechnology

### ➤ TO220F



### ➤ Application

- SMPS Power Supplier
- Charger Adapter
- Power Tools
- LED Lighting

### ➤ Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, $V_{GS} @ 10V_1$	$I_D @ T_C=25^\circ C$	30	A
Continuous Drain Current, $V_{GS} @ 10V_1$	$I_D @ T_C=100^\circ C$	20	A
Continuous Drain Current, $V_{GS} @ 10V_1$	$I_D @ T_A=25^\circ C$	7.4	A
Continuous Drain Current, $V_{GS} @ 10V_1$	$I_D @ T_A=70^\circ C$	6	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	90	A
Single Pulse Avalanche Energy <sup>3</sup>	EAS	39	mJ
Avalanche Current	$I_{AS}$	28	A
Total Power Dissipation <sup>4</sup>	$P_D @ T_C=25^\circ C$	30	W
Total Power Dissipation <sup>4</sup>	$P_D @ T_A=25^\circ C$	2	W
Storage Temperature Range	$T_{STG}$	-55 to 150	$^\circ C$
Operating Junction Temperature Range	$T_J$	-55 to 150	$^\circ C$
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	62	$^\circ C/W$
Thermal Resistance Junction-Case <sup>1</sup>	$R_{\theta JC}$	4.2	$^\circ C/W$

### ➤ Electrical Characteristics ( $T_J=25^\circ C$ Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V$ , $I_D=250\mu A$	60	---	---	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^\circ C$ , $I_D=1mA$	---	0.057	---	V/ $^\circ C$
Static Drain-Source On-Resistance <sup>2</sup>	$R_{DS(ON)}$	$V_{GS}=10V$ , $I_D=15A$	---	---	20	$m\Omega$
		$V_{GS}=4.5V$ , $I_D=10A$	---	---	24	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}$ , $I_D=250\mu A$	1.2	---	2.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		---	-5.68	---	mV/ $^\circ C$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=48V$ , $V_{GS}=0V$ , $T_J=25^\circ C$	---	---	1	$\mu A$
		$V_{DS}=48V$ , $V_{GS}=0V$ , $T_J=55^\circ C$	---	---	5	
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V$ , $V_{DS}=0V$	---	---	$\pm 100$	nA
Forward Transconductance	$g_{fs}$	$V_{DS}=5V$ , $I_D=15A$	---	39	---	S
Gate Resistance	$R_g$	$V_{DS}=0V$ , $V_{GS}=0V$ , $f=1MHz$	---	1.7	---	$\Omega$
Total Gate Charge (4.5V)	$Q_g$	$V_{DS}=48V$ , $V_{GS}=4.5V$ , $I_D=15A$	---	19.3	---	nC
Gate-Source Charge	$Q_{gs}$		---	7.1	---	
Gate-Drain Charge	$Q_{gd}$		---	7.6	---	
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=30V$ , $V_{GS}=10V$ , $R_G=3.3\Omega$ , $I_D=15A$	---	7.2	---	ns
Rise Time	$T_r$		---	50	---	
Turn-Off Delay Time	$T_{d(off)}$		---	36.4	---	
Fall Time	$T_f$		---	7.6	---	
Input Capacitance	$C_{iss}$	$V_{DS}=15V$ , $V_{GS}=0V$ , $f=1MHz$	---	2423	---	pF
Output Capacitance	$C_{oss}$		---	145	---	
Reverse Transfer Capacitance	$C_{rss}$		---	97	---	

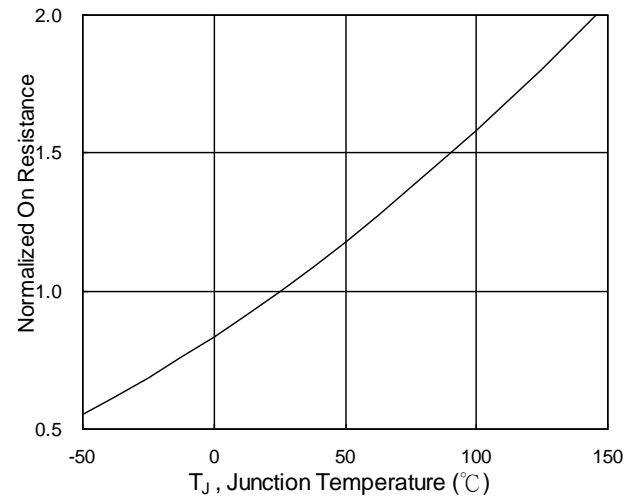
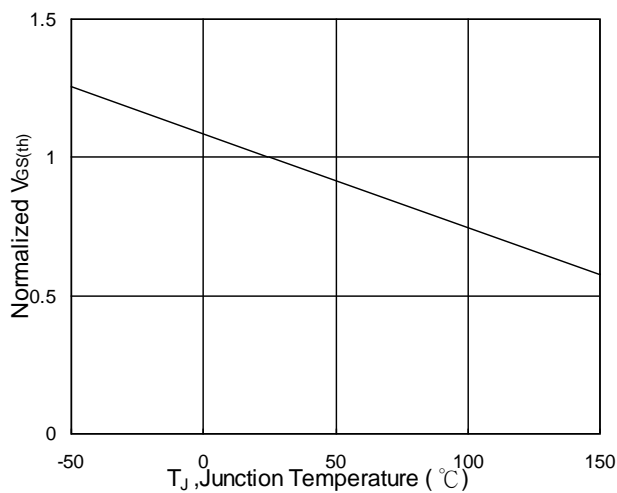
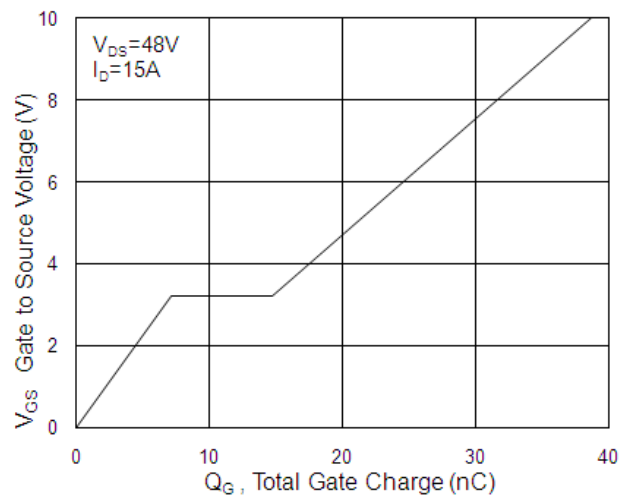
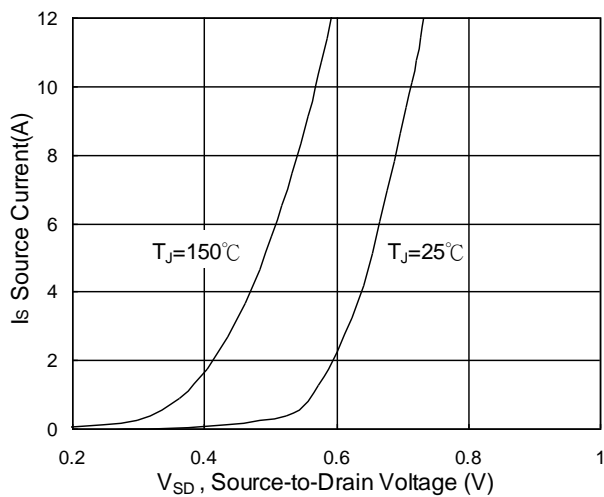
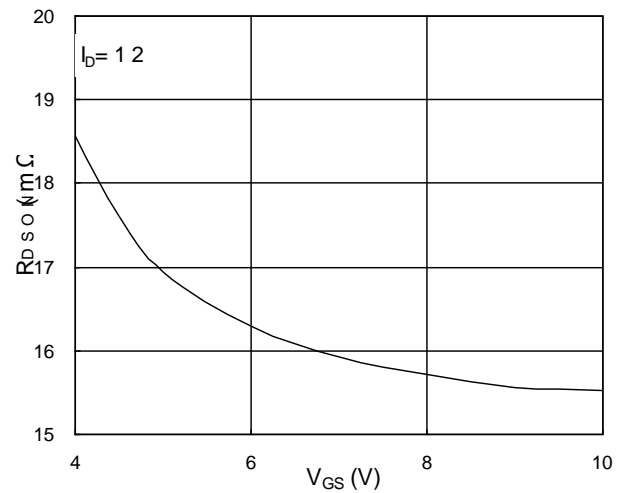
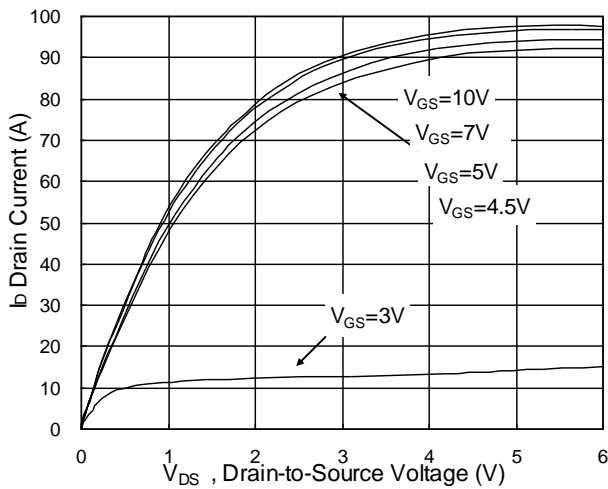
### ➤ Diode Characteristics

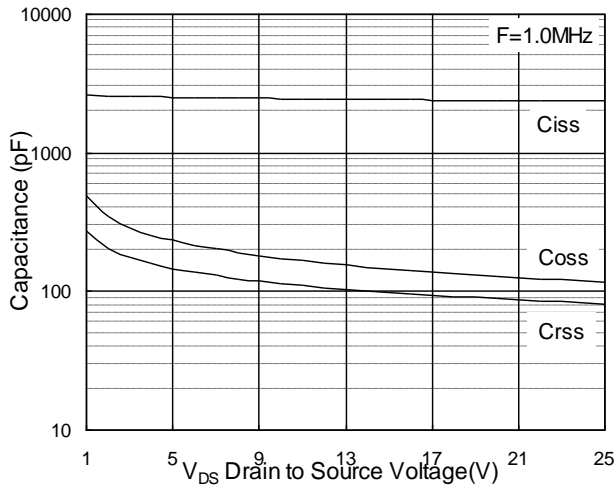
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current <sup>1,5</sup>	$I_S$	$V_G=V_D=0V$ , Force Current	---	---	30	A
Pulsed Source Current <sup>2,5</sup>	$I_{SM}$		---	---	90	A
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	$V_{GS}=0V$ , $I_S=1A$ , $T_J=25^\circ C$	---	---	1	V
Reverse Recovery Time	$t_{rr}$	$I_F=15A$ , $dI/dt=100A/\mu s$ , $T_J=25^\circ C$	---	16.3	---	nS
Reverse Recovery Charge	$Q_{rr}$		---	11	---	nC

Note :

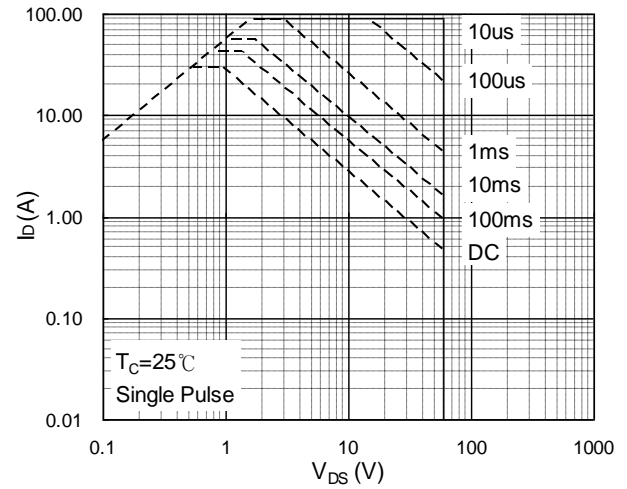
1. Pulse width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating. The test condition is  $V_{DD}=25V$ ,  $V_{GS}=10V$ ,  $L=0.1mH$ ,  $I_{AS}=28A$
4. Ensure that the channel temperature does not exceed  $150^\circ C$ .
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

### ➤ Typical Characteristics

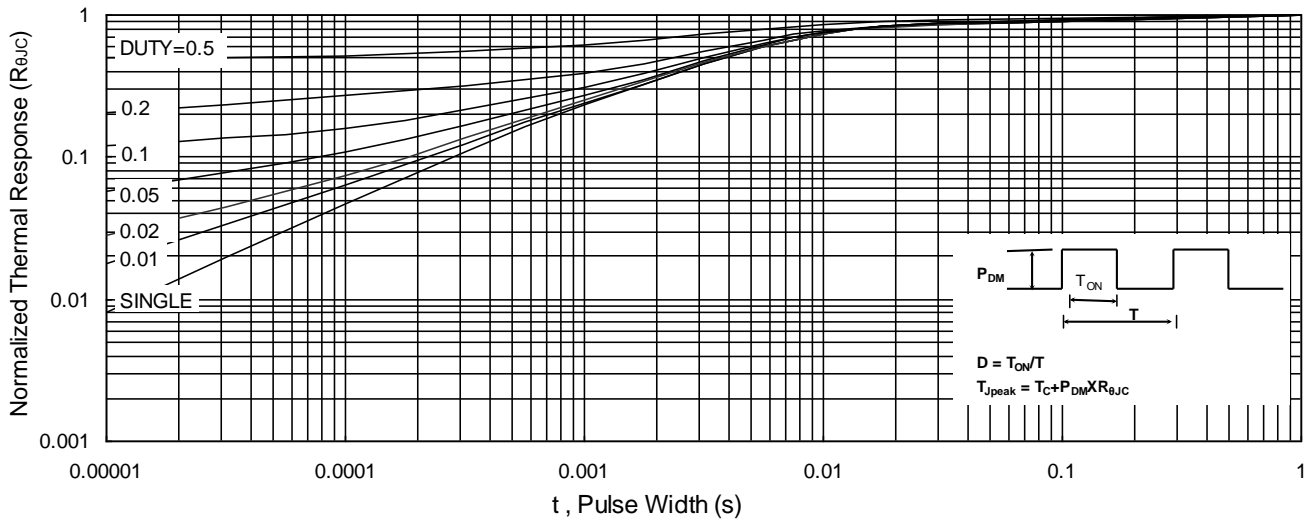




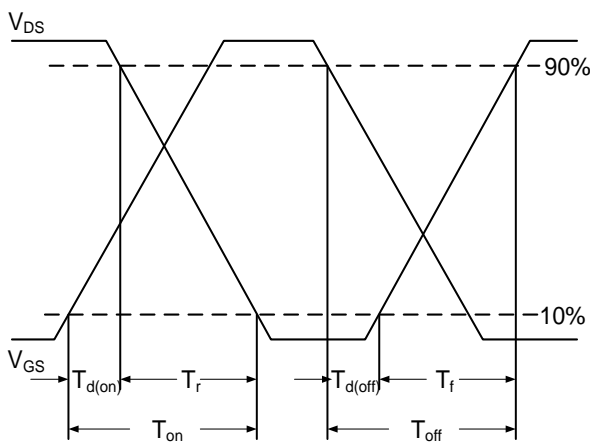
**Fig.7 Capacitance**



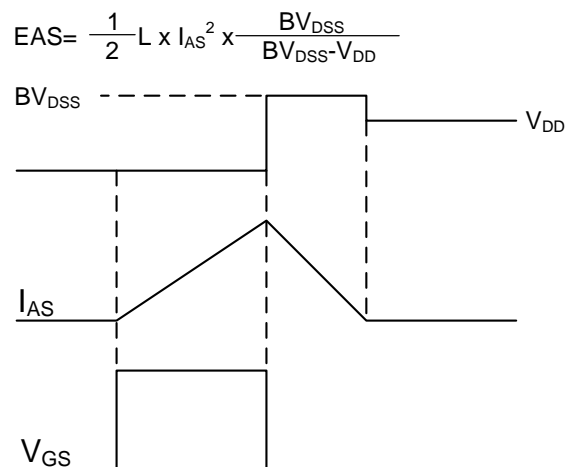
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

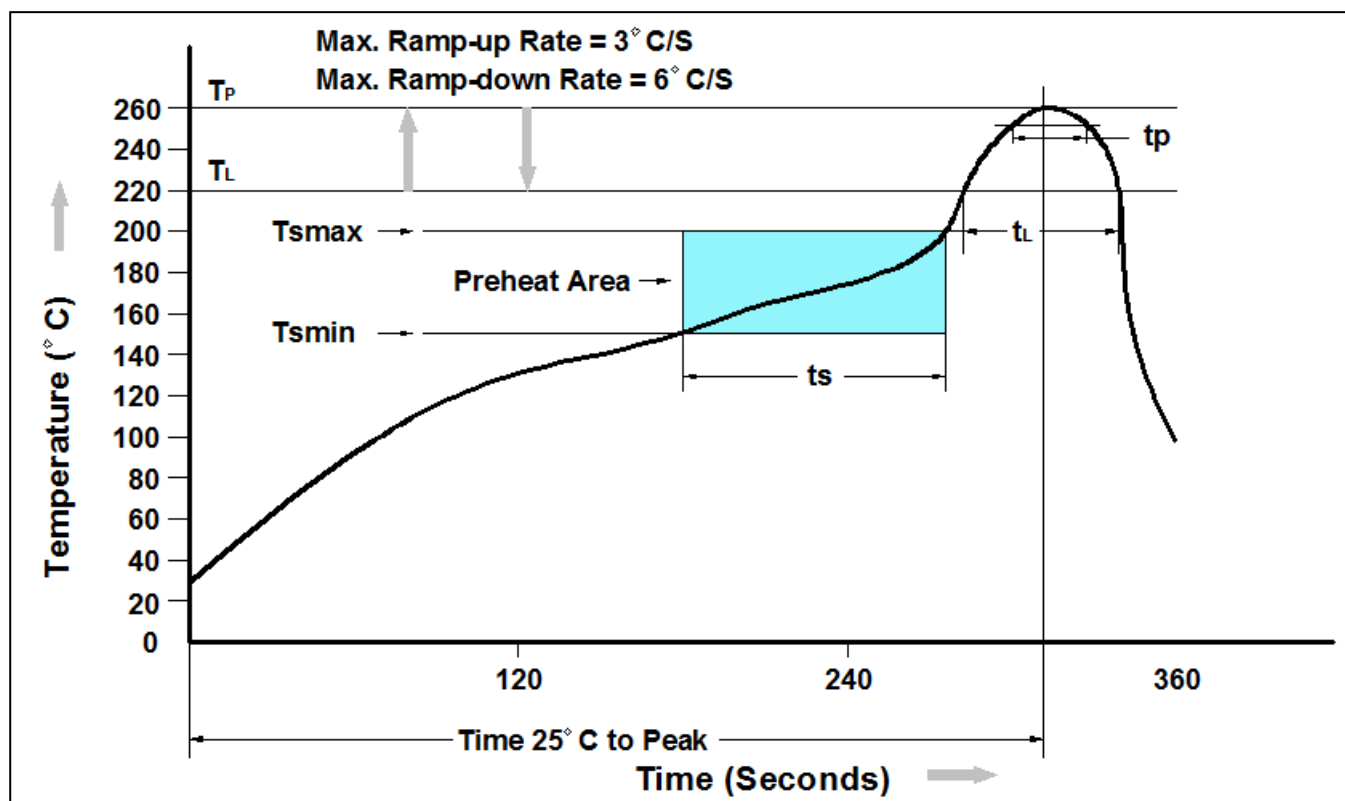


**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**

### ➤ Recommend IR Reflow Soldering Thermal Profile

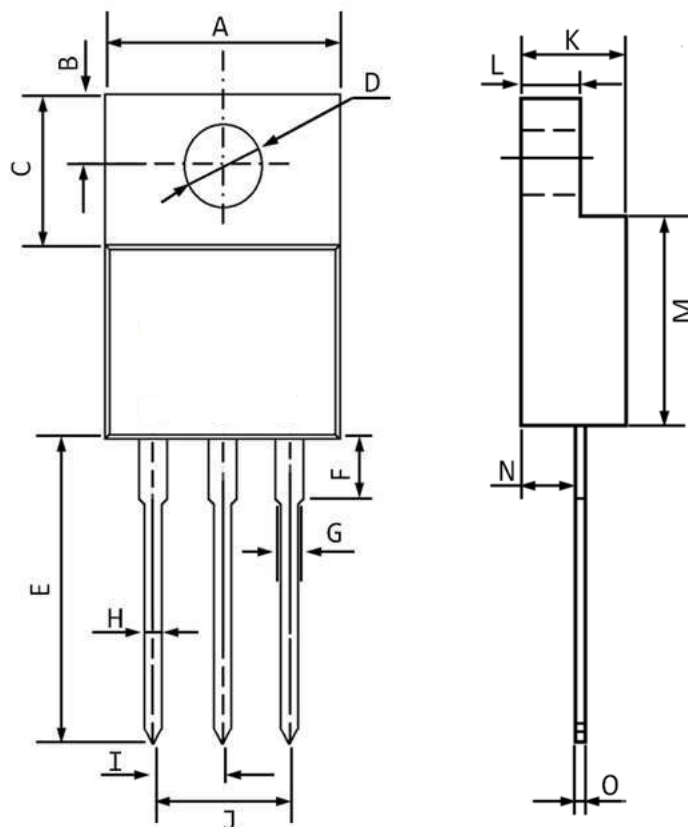


Profile Feature	Pb-Free Assembly Profile
Temperature Min. ( $T_{Smin}$ )	150°C
Temperature Max. ( $T_{Smax}$ )	200°C
Time ( $t_S$ ) from ( $T_{Smin}$ to $T_{Smax}$ )	60-120 seconds
Average Ramp-up Rate ( $t_L$ to $t_P$ )	3°C/second max.
Liquidous Temperature ( $T_L$ )	217°C
Time ( $t_L$ ) Maintained Above ( $T_L$ )	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time ( $t_P$ ) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate ( $T_P$ to $T_L$ )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

### ➤ Ordering Information

Part Number	Description	Quantity
PAN60TF06GF	TO-220F / 50 pcs/tube	1000 pcs

### ➤ Package Information ( TO-220F )



SYMBOLS	MILLIMETERS		INCHES	
	Min.	Max.	Min.	Max.
A	—	10.50	—	0.414
B	2.60	3.00	0.102	0.118
C	6.70	7.10	0.264	0.280
D	2.90	3.50	0.114	0.138
E	13.10	13.90	0.516	0.548
F	—	4.00	—	0.158
G	1.11	1.45	0.044	0.057
H	0.40	0.80	0.016	0.032
I	2.40	2.80	0.095	0.110
J	5.00	5.40	0.197	0.213
K	4.30	4.70	0.169	0.185
L	2.90	3.30	0.114	0.130
M	8.20	9.00	0.323	0.355
N	2.50	2.90	0.099	0.114
O	0.40	0.80	0.016	0.032

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